

IN THE CLAIMS

1. (previously presented) A multi-functioned wafer aligner comprising:
 - a multi-functioned unit for performing wafer centering, wafer flat zone alignment, and wafer damage detection;
 - the multi-functioned unit comprising:
 - a wafer rotator;
 - an array of luminous emitters for emitting incident rays toward a wafer disposed on the wafer rotator; and
 - an array of damage-detecting sensors for receiving the incident rays reflected from edges of the wafer to detect wafer damage; and
 - a processor for determining positions of the wafer centering and the wafer flat zone alignment, and wafer damage by calculating an accumulated digital signal inputted from the multi-functioned unit.
 2. (previously presented) The multi-functioned wafer aligner of claim 1, wherein the multi-functioned unit further comprises:
 - an array of photo detecting sensors for receiving the incident rays emitted from the array of luminous emitters to detect a wafer position and a wafer flat zone, wherein the photo detecting sensors are disposed opposed to the luminous emitters.
 3. (previously presented) The multi-functioned wafer aligner of claim 2, wherein the array of photo detecting sensors receive no incident ray when the wafer interrupts the incident rays from the array of luminous emitters.

4. (previously presented) The multi-functioned wafer aligner of claim 6, wherein the processor further comprises an alarm unit when the second area receives reflected rays.
5. (previously presented) The multi-functioned wafer aligner of claim 1, wherein the multi-functioned unit comprises an array of luminous emitters for emitting incident rays to the edge of the wafer.
6. (previously presented) The multi-functioned wafer aligner of claim 1, wherein a first area in the array of damage-detecting sensors receives reflected rays when the wafer is not damaged, and a second area in the array of damage-detecting sensors receives reflected rays when the wafer is damaged.
7. (previously presented) A multi-functioned wafer aligner comprising:
 - a rotatable chuck, adapted to receive a semiconductor wafer;
 - a wafer transfer unit, adapted to position said wafer upon said rotatable chuck;
 - a sensor body, comprising:
 - a position compensator for performing wafer centering;
 - a luminous source; and
 - a wafer damage detector comprising an array of damage-detecting sensors adapted to receive light emitted from said luminous source that is reflected off of the edge of said wafer;
 - wherein said sensor body is disposed in relation to said rotatable chuck so as to receive an edge of said wafer within said position compensator.

8. (previously presented) The apparatus of claim 7, wherein said position compensator comprises:

a photodetector disposed upon an opposing side of the luminous source, said photodetector adapted to receive light emitted by said luminous source.

9. canceled

10. (previously presented) A method for positioning a wafer and detecting wafer damage, said method comprising:

providing a luminous source on a first side of an edge of said wafer;

providing a photodetector on an opposing side of said wafer, said photodetector adapted to receive light emitted by said luminous source;

providing an array of damage-detecting sensors adapted to receive light emitted from said luminous source that is reflected off of said wafer edge;

rotating said wafer;

determining the position of said wafer by examination of light received by said photodetector; and

inspecting for damage to said wafer by examining the light received by said array of damage-detecting sensors.